

## ABSTRACT OF THE DISCLOSURE

An electronic component mount structure includes a printed circuit board, a wiring portion, a through-holed portion, a heat conducting apertured portion and an electronic component. The printed circuit board has a component mount surface and a solder-dip surface. The wiring portion is formed on at least one of the component mount surface and the solder-dip surface. The through-holed portion extends through the circuit board and is connected to be electrically conductive with the wiring portion. The heat conducting apertured portion extends through the circuit board and is connected to be electrically conductive with the wiring portion. Here, the heat conducting apertured portion is formed in the vicinity of the through-holed portion. A lead portion of the electronic component is inserted to the through-holed portion of the printed circuit board from the component mount surface and soldered to the printed circuit board.